# Chip tantalum capacitors with open-function built-in

# **TCFG series P Case**

#### Features

- 1) Safety design by open function built in.
- 2) Wide capacitance range
- 3) Screening by thermal shock.

# •External dimensions (Unit : mm)



Case code	L	W1	W2	Н	S
P (2012)	2.0±0.2	1.25±0.2	0.9±0.2	Max.1.20	0.45±0.3

#### Product designation 5 G (1)(4) Capacitance (1) Series name TCFG Nominal capacitance in pF in 3 digits : 2significant figure representing the number of 0's. (2) Case code TCFG ····· P (5) Capacitance tolerance M: ±20% K: ±10% (3) Rated Voltage Rated voltage (V) 4 6.3 10 16 20 25 CODE 0G 0J 1A 1C 1D 1E (6) Taping 8 : Tape width (8mm) R : Positive electrode on the side opposite to sprocket hole

#### Capacitance range

TCFG series P Case

			Rated	/oltage		
(μF)	4 0G	6.3 0J	10 1A	16 1C	20 1D	25 1E
1.0 (105)			Р	Р	Р	Р
1.5 (155)		Р	Р	Р		
2.2 (225)	Р	Р	Р	Р		
3.3 (335)	Р	Р	Р	Р		
4.7 (475)	Р	Р	Р			
6.8 (685)	Р	Р				
10 (106)	Р	Р				
15 (156)	Р	Р				
22 (226)	Р					
33 (336)						
47 (476)						
68 (686)						

Remark) Case size codes (P) in the above show each size products line-up.

#### Marking

[P Case]

The indications listed below should be given on the surface of a capacitor.

① Polarity : The polarity should be shown by  $\Box$  bar. (on the anode side)

2 Rated DC voltage : Due to the small size of P case, a voltage code is used as shown below.

(3) Nominal capacitance

Voltage Code	Rated DC Voltage (V)
g	4
j	6.3
A	10
С	16
D	20
E	25

Capacitance Code	Nominal Capacitance (µF)
А	1.0
E	1.5
J	2.2
N	3.3
S	4.7
W	6.8
а	10
e	15
j	22

Visual typical example (1) voltage code (2) capacitance code



note 2) voltage code and capacitance code are variable with parts number

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#### Characteristics

lterr	ו	Performance				(base			onditions 1-1 and JIS C5	5101-3)				
Operating Temperature -55 °C to +125 °C			Voltage reduction when temperature exceeds +85°C			eds +85°C								
Maximum operatir with no voltage de		+8	5 °C											
Rated Voltage	(V.DC)	4	6.3	10 1	6 20	2	25		at	85°C				
Category Volta	ge (V.DC)	2.5	4	6.3 1	0 13	1	16		at	125°C				
Surge Voltage		5.2	8	13 2	0 26	; 3	32		at	85°C				
DC leakage cu	rrent			or 0.01 n in "St				er is greater	As	per 4.	9 JIS C 5.1 JIS Rated v	C 5101		
Capacitance to	lerance		Shall be satisfied allowance range. ±10%, ±20%				As Me Me	As per 4.7 JIS C 5101-1 As per 4.5.2 JIS C 5101-3 Measuring frequency : 120±12Hz Measuring voltage : 0.5Vrms, +1.5V.DC Measuring circuit : DC Equivalent series circ						
Tangent of loss (Df, tanδ)	s angle	Sh	Shall be satisfied the voltage on "Standard list"			st" As per 4.8 JIS C 5101-1 As per 4.5.3 JIS C 5101-3 Measuring frequency : 120±12Hz Measuring voltage : 0.5Vrms, +1.5V.DC Measuring circuit : DC Equivalent seri								
Impedance	mpedance Shall be satisfied the voltage on "Standard list"			As Me Me	As per 4.10 JIS C 5101-1 As per 4.5.4 JIS C 5101-3 Measuring frequency : 100±10kHz Measuring voltage : 0.5Vrms or less Measuring circuit : DC Equivalent series circuit									
Resistance to soldering heat	Appearance		There should be no significant abnormality. The indications should be clear.				As per 4.14 JIS C 5101-1 As per 4.6 JIS C 5101-3							
	L.C	Le	ss th	an initia	al limit					Dip in the solder bath Solder temp : 260±5°C Duration : 5±0.5s				
	ΔC / C	Wi	thin ±	10% (	of initi	al v	alu	9						
	tanδ	Le	Less than 150% of initial limit				Repetition : 1							
Fail-Safe open	unit actuation	Wi	thin (	320°C	– 20s	5			Dip	Dip in the solder bath Solder temp : 320±5°C				
Temperature cycle	Appearance	Th	ere s	hould	be no	sigr	nific	ant abnormality.	As per 4.16 JIS C 5101-1 As per 4.10 JIS C 5101-3					
	L.C	Le	ss th	an initia	al limit					•		•	cycle : steps 1	to 4)
	ΔC / C							f initial value		Step		mp.	Time	1
	tans			•				f initial value	_	1		±3°C	30±3min	
	tanδ	Le	รรเก	an 150	% 01 II	nua	ai iir	IIL		2		temp.	3min. or less	1
										3	125	±2°C	30±3min	
										4	Room	temp.	3min. or less	
Moisture resistance	Appearance			hould l		0		ant abnormality. lear.	As per 4.22 JIS C 5101-1 As per 4.12 JIS C 5101-3					
	L.C	Le	ss th	an initia	al limit								e under such a	
	-	Within ±20% of initial value					- condition that the temperature and humidity are $60\pm2^{\circ}$ C and 90 to 95%RH, respectively, for							
	ΔC / C	Wi	thin ±	20% (	of initi	al v	alu	9	60	±2°C a	nd 90 to	95%F		y, for

Iter	n	Performance	Test conditions (based on JIS C5101-1 and JIS C5101-3)			
Temperature Temp. Stability		–55°C	As per 4.29 JIS C 5101-1			
Stability	∆C / C	Within 0/–15%of initial value	As per 4.13 JIS C 5101-3			
	tanδ	Shall be satisfied the voltage on "Standard list"				
	L.C	-				
	Temp.	+85°C				
	ΔC / C	Within +15/0%of initial value				
	tanδ	Shall be satisfied the voltage on "Standard list"				
	L.C	5μA or 0.1CV whichever is greater				
	Temp.	+125°C				
	ΔC / C	Within +20/0%of initial value				
	tanδ	Shall be satisfied the voltage on "Standard list"				
	L.C	6.3µA or 0.125CV whichever is greater				
Surge	Appearance	There should be no significant abnormality.	As per 4.26 JIS C 5101-1			
Voltage	L.C	Shall be satisfied the voltage on "Standard list"	As per 4.14 JIS C 5101-3 Apply the specified surge voltage every 5±0.5mi			
	ΔC / C	Within ±10%of initial value	for 30±5 s. each time in the atmospheric condition			
	tanδ	Less than 150% of initial limit	of 85±2°C. Repeat this procedure 1,000 times.			
Loading at	Appearance	There should be no significant abnormality.	As per 4.23 JIS C 5101-1			
High temperature	L.C	Less than initial limit	As per 4.15 JIS C 5101-3 — After applying the rated voltage for 1000+36/0			
	ΔC / C	Within ±10%of initial value	without discontinuation via the serial resistanc			
	tanδ	Less than 150% of initial limit	<ul> <li>of 3Ω or less at a temperature of 85±2°C, leav the sample at room temperature/humidity for 1 to 2h and measure the value.</li> </ul>			
Terminal	Capacitance	The measured value should be stable.	As per 4.35 JIS C 5101-1			
Strength	Appearance	There should be no significant abnormality.	As per 4.9 JIS C 5101-3 A force is applied to the terminal until it bends to 1mm and by a prescribed tool maintain the condition for 5s. (See the figure below.) $50 \xrightarrow{20}$ F (Apply force) R230 + 1 Thickness 1.6mm			
Adhesiveness		The terminal should not come off.	As per 4.34 JIS C 5101-1 As per 4.8 JIS C 5101-3 Apply force of 5N in the two directions shown in the figure below for 10±1s after mounting the terminal on a circuit board.			

Item		Performance	Test conditions (based on JIS C5101-1 and JIS C5101-3)		
Dimensio	ns	Be based on "External dimensions"	Measure using a caliper of JIS B 7505 Class 2 or higher grade.		
Solderability 3/4 or n termina		The indication should be clear.	As per 4.32 JIS C 5101-1 As per 4.18 JIS C 5101-3 Dip in the isopropyl alcohol for 30±5s, at room temperature.		
		3/4 or more surface area of the solder coated terminal dipped in the soldering bath should be covered with the new solder.	As per 4.15.2 JIS C 5101-1 As per 4.7 JIS C 5101-3 Dip speed = 25±2.5mm/s Pre-treatment (accelerated aging) : Leave th sample on the boiling distilled water for 1h. Solder temp. : 235±5°C Duration : 2±0.5s Solder : H63A Flux : Rosin 25%, IPA 75%		
Vibration Capacitance Appearance		Measure value should not fluctuate during the measurement. There should be no significant abnormality.	As per 4.17 JIS C 5101-1 Frequency : 10 to 55 to 10Hz/min. Amplitude : 1.5mm Time : 2h each in X and Y directions		
			Mounting : The terminal is soldered on a print circuit board.		

										(P :	2012)
Part No.		Capacitance 120Hz	120Hz Tolerance	Leakage current 25°C	DF120Hz (%)			Impedance 100kHz	Case		
	(V)	(V)	(V)	(μF)	(%)	1WV.60s (mA)	–55° <b>C</b>	25°C 85°C	125°C	(Ω)	code
TCFG P 0G 225 □	4	2.5	5.2	2.2	±20,±10	0.5	15	10	15	4.0	Р
TCFG P 0G 335 □	4	2.5	5.2	3.3	±20,±10	0.5	30	20	30	17.5	Р
TCFG P 0G 475□	4	2.5	5.2	4.7	±20,±10	0.5	30	20	30	14.4	Р
TCFG P 0G 685 □	4	2.5	5.2	6.8	±20,±10	0.5	30	20	30	11.8	Р
TCFG P 0G 106□	4	2.5	5.2	10	±20,±10	0.5	30	20	30	9.3	Р
TCFG P 0G 156 □	4	2.5	5.2	15	±20,±10	0.6	30	20	30	8.3	Р
TCFG P 0G 226 □	4	2.5	5.2	22	±20,±10	0.9	30	20	30	7.7	Р
TCFG P 0J 155 🗆	6.3	4	8	1.5	±20,±10	0.5	15	10	15	17.5	Р
TCFG P 0J 225□	6.3	4	8	2.2	±20,±10	0.5	30	20	30	4.0	Р
TCFG P 0J 335□	6.3	4	8	3.3	±20,±10	0.5	30	20	30	14.4	Р
TCFG P 0J 475□	6.3	4	8	4.7	±20,±10	0.5	30	20	30	11.8	Р
TCFG P 0J 685□	6.3	4	8	6.8	±20,±10	0.5	30	20	30	9.3	Р
TCFG P 0J 106□	6.3	4	8	10	±20,±10	0.6	30	20	30	8.3	Р
TCFG P 0J 156□	6.3	4	8	15	±20,±10	0.9	30	20	30	7.7	Р
TCFG P 1A 105□	10	6.3	13	1.0	±20,±10	0.5	15	10	15	17.5	Р
TCFG P 1A 155□	10	6.3	13	1.5	±20,±10	0.5	30	20	30	16.1	Р
TCFG P 1A 225□	10	6.3	13	2.2	±20,±10	0.5	30	20	30	4.0	Р
TCFG P 1A 335□	10	6.3	13	3.3	±20,±10	0.5	30	20	30	11.8	Р
TCFG P 1A 475	10	6.3	13	4.7	±20,±10	0.5	30	20	30	6.0	Р
TCFG P 1C 105 🗆	16	10	20	1.0	±20,±10	0.5	15	10	15	16.5	Р
TCFG P 1D 105 🗆	20	13	26	1.0	±20,±10	0.5	15	10	15	16.1	Р
TCFG P 1E 105 🗆	25	16	33	1.0	±20,±10	0.5	15	10	15	16.1	Р
- Tolerance (M · +2	0% K·⊥1	00/)									

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#### •Table 1 standard list, TCFG series P Case

□=Tolerance (M : ±20%, K : ±10%)

#### Packaging specifications

Case code	A±0.1	B±0.1	t1±0.05	t2±0.1
P (2012)	1.55	2.3	0.25	1.5



# TCFG series P Case

#### Tantalum capacitors

# Packaging style

Case size	Packaging	Packag	ing style	Symbol	Basic ordering unit	
P Case	Taping	Plastic taping	φ180mm reel	R	2,000	



# rohm

# (1) Soldering Conditions (°C) 250 Reflow heating rate ③

• Recommended condition of reflow soldering



#### Recommended condition of reflow soldering

①Pre heating rate	: 1 to 5°C/ s
②Preliminary heating	: 120 to 160°C, 50 to 120s
③Reflow heating rate	: 1 to 5°C / s
④Soldering	: 200°C, 30 to 60s
⑤Peak temperature	: 230 to 260°C 10s Max.
6 Cooling	: 60s Min.
⑦Time	: 2times Max.

#### Recommended condition of hand soldering

①Temperature (30W Max.)	: 300°C Max.
②Time	: 5s Max.

# ②Time

#### Flow soldering (Dip . Wave soldering)



(2) Leakage current-to-voltage ratio



(3) Derating voltage as function of temperature



Fig.3

#### (4) Reliability

The malfunction rate of tantalum solid state electrolytic capacitors varies considerably depending on the conditions of usage (ambient temperature, applied voltage, circuit resistance).

#### Formula for calculating malfunction rate

 $\lambda p = \lambda b \times (\pi E \times \pi SR \times \pi Q \times \pi CV)$ 

- $\lambda p$  : Malfunction rate stemming from operation
- $\lambda b \quad : \text{Basic malfunction rate} \quad$
- $\pi_{\text{E}}$  : Environmental factors
- πSR : Series resistance
- $\pi_Q$ : Level of malfunction rate
- πcv : Capacitance

For details on how to calculate the malfunction rate stemming from operation, see the tantalum solid state electrolytic capacitors column in MIL-HDBK-217.



Fig.4

(5) External temperature vs. fuse blowout



Malfunction rate as function of circuit resistance ( $\Omega N$ )





(6) Power vs. fuse blowout characteristics / Product surface temperature



Note: Solder the chip at 300°C or less. If it is soldered using a temperature higher than 300°C, open function built-in may operate.

#### (7) Maximum power dissipation

Warming of the capacitor due to ripple voltage balances with warming caused by Joule heating and by radiated heat. Maximum allowable warming of the capacitor is to 5°C above ambient temperature. When warming exceeds 5°C, it can damage the dielectric and cause a short circuit.

Power dissipation (P) =  $I^2 \cdot R$ 

**Ripple current** 

- P: As shown in table at right
- R : Equivalent series resistance

Notes:

1. Please be aware that when case size is changed, maximum allowable power dissipation is reduced.

2. Maximum power dissipation varies depending on the package. Be sure to use a case which will keep warming within the limits shown in the table below.



Case Ambient temp	+25°C	+55°C	+85°C	+125°C
P case (2012)	0.025	0.022	0.020	0.010
Max. Temp Rise (°C)	5	5	5	2

#### Allowable power dissipation (W) and maximum temperature rising

#### (8) Impedance frequency characteristics

(10) Temperature characteristics

1(

CHANGE (%)

CAP

-10 -55



CAP 120Hz

- 10V-1μF P case (2012) - 4V-4.7μF A case (3216) - 4V-33μF B case (3528)

85

TEMPERATURE (°C)

Fig.10

25

125

#### (9) ESR frequency characteristics





# DF 120Hz ---10V-1µF P case (2012) --4V-4.7µF A case (3216) ---4V-33µF B case (3528) ---4V-34µF B case (3528)<

Fig.11







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#### Inrush current

Inrush current can be limited by means of a protective resistor.



(11) Ultrasonic cleaning

Carry out cleaning under as mild conditions as possible. The internal element of a tantalum capacitor are larger than those of a transistor or diode, so it is not as resistant as ultrasonic waves.

Example : water Propagation speed Solvent density

1500m / s 1g / cm<sup>3</sup>

Frequency and wavelength

Frequency	Wavelength	
20kHz	7.5cm	
28kHz	5.3cm	
50kHz	3.0cm	

#### Precautions

- 1) Do not allow solvent to come to a boil (kinetic energy increases).
- . Ultrasonic output 0.5W / cm<sup>2</sup> or less
- . Use a solvent with a high boiling point.
- . Lower solvent temperature.
- 2) Ultrasonic cleaning frequency 28 kHz or less
- 3) Keep cleaning time as short as possible.
- 4) Move item being cleaned. Standing waves caused by the ultrasonic waves can cause stress to build up in part of the item being cleaned.

Reference

Kin etic energy =  $2 \times \pi \times$  frequency  $\times \sqrt{\frac{2 \times \text{Ultrasonic output}}{\text{propagation} \times \text{speed} \times \text{solvent density}}}$ 

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